

LM2672 SIMPLE SWITCHER® Power Converter High Efficiency 1A Step-Down Voltage **Regulator with Features**

Check for Samples: LM2672

FEATURES

- Efficiency up to 96%
- Available in SOIC-8 and 8-pin PDIP Packages
- Computer Design Software LM267X Made Simple Version 6.0
- Simple and Easy to Design with
- **Requires only 5 External Components**
- **Uses Readily Available Standard Inductors**
- 3.3V, 5.0V, 12V, and Adjustable Output Versions
- **Adjustable Version Output Voltage Range:** 1.21V to 37V
- ±1.5% Max Output Voltage Tolerance Over **Line and Load Conditions**
- **Specified 1A Output Load Current**
- 0.25Ω DMOS Output Switch
- Wide Input Voltage Range: 8V to 40V
- 260 kHz Fixed Frequency Internal Oscillator
- TTL Shutdown Capability, Low Power Standby Mode
- **Soft-Start and Frequency Synchronization**
- Thermal Shutdown and Current Limit **Protection**

TYPICAL APPLICATIONS

- Simple High Efficiency (>90%) Step-Down (Buck) Regulator
- **Efficient Pre-Regulator for Linear Regulators**

DESCRIPTION

The LM2672 series of regulators are monolithic integrated circuits built with a LMDMOS process. These regulators provide all the active functions for a step-down (buck) switching regulator, capable of driving a 1A load current with excellent line and load regulation. These devices are available in fixed output voltages of 3.3V, 5.0V, 12V, and an adjustable output version.

Requiring minimum number of а external components, these regulators are simple to use and include patented internal frequency compensation (Patent Nos. 5,382,918 and 5,514,947), fixed frequency oscillator, external shutdown, soft-start, and frequency synchronization.

The LM2672 series operates at a switching frequency of 260 kHz, thus allowing smaller sized filter components than what would be needed with lower frequency switching regulators. Because of its very high efficiency (>90%), the copper traces on the printed circuit board are the only heat sinking needed.

A family of standard inductors for use with the LM2672 are available from several different manufacturers. This feature greatly simplifies the design of switch-mode power supplies using these advanced ICs. Also included in the datasheet are selector guides for diodes and capacitors designed to work in switch-mode power supplies.

Other features include a ensured ±1.5% tolerance on output voltage within specified input voltages and output load conditions, and ±10% on the oscillator frequency. External shutdown is included, featuring typically 50 µA stand-by current. The output switch includes current limiting, as well as thermal shutdown for full protection under fault conditions.

To simplify the LM2672 buck regulator design procedure, there exists computer design software, LM267X Made Simple version 6.0.

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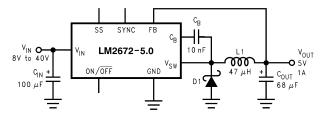
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Typical Application

(Fixed Output Voltage Versions)



Connection Diagram

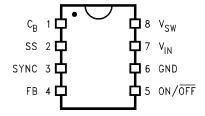


Figure 1. 8-Lead Package SOIC-8/PDIP Package See Package Drawing Numbers D (R-PDSO-G8)/P (R-PDIP-T8) Top View

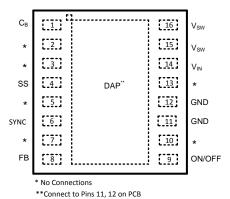


Figure 2. 16-Lead WSON Surface Mount Package See Package Drawing Number NHN0016A Top View



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



Absolute Maximum Ratings(1)(2)

Supply Voltage		45V		
ON/OFF Pin Voltage		-0.1V ≤ V _{SH} ≤ 6V		
Switch Voltage to Ground	-1V			
Boost Pin Voltage		V _{SW} + 8V		
Feedback Pin Voltage		-0.3V ≤ V _{FB} ≤ 14V		
ESD Susceptibility	Human Body Model (3)	2 kV		
Power Dissipation	•	Internally Limite		
Storage Temperature Range		−65°C to +150°C		
Lead Temperature				
D Package	Vapor Phase (60s)	+215°C		
	Infrared (15s)	+220°C		
PDIP Package (Soldering, 10s)		+260°C		
Maximum Junction Temperature	·	+150°C		

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but device parameter specifications may not be ensured under these conditions. For specific specifications and test conditions, see the Electrical Characteristics.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (3) The human body model is a 100 pF capacitor discharged through a 1.5 k Ω resistor into each pin.

Operating Ratings

Supply Voltage	6.5V to 40V
Temperature Range	-40°C ≤ T _J ≤ +125°C

LM2672-3.3 Electrical Characteristics

Specifications with standard type face are for $T_J = 25$ °C, and those in **bold type face** apply over **full Operating Temperature Range.**

ago.									
Symbol	Parameter	Conditions	Typ ⁽¹⁾	Min ⁽²⁾	Max ⁽²⁾	Units			
SYSTEM PARAMETERS Test Circuit Figure 22 ⁽³⁾									
V _{OUT}	Output Voltage	V_{IN} = 8V to 40V, I_{LOAD} = 20 mA to 1A	3.3	3.251/ 3.201	3.350/ 3.399	V			
V _{OUT}	Output Voltage	V_{IN} = 6.5V to 40V, I_{LOAD} = 20 mA to 500 mA	3.3	3.251/ 3.201	3.350/ 3.399	V			
η	Efficiency	$V_{IN} = 12V$, $I_{LOAD} = 1A$	86			%			

- (1) Typical numbers are at 25°C and represent the most likely norm.
- (2) All limits specified at room temperature (standard type face) and at temperature extremes (bold type face). All room temperature limits are 100% production tested. All limits at temperature extremes are specified via correlation using standard Statistical Quality Control (SQC) methods. All limits are used to calculate Average Outgoing Quality Level (AOQL).
- (3) External components such as the catch diode, inductor, input and output capacitors, and voltage programming resistors can affect switching regulator performance. When the LM2672 is used as shown in Figure 22 and Figure 23 test circuits, system performance will be as specified by the system parameters section of the Electrical Characteristics.

LM2672-5.0 Electrical Characteristics

Symbol	Parameter	Conditions	Typ ⁽¹⁾	Min ⁽²⁾	Max ⁽²⁾	Units		
SYSTEM PARAMETERS Test Circuit Figure 22 ⁽³⁾								
V _{OUT}	Output Voltage	V_{IN} = 8V to 40V, I_{LOAD} = 20 mA to 1A	5.0	4.925/ 4.850	5.075/ 5.150	V		
V _{OUT}	Output Voltage	V_{IN} = 6.5V to 40V, I_{LOAD} = 20 mA to 500 mA	5.0	4.925/ 4.850	5.075/ 5.150	V		
η	Efficiency	V _{IN} = 12V, I _{LOAD} = 1A	90			%		

- (1) Typical numbers are at 25°C and represent the most likely norm.
- (2) All limits specified at room temperature (standard type face) and at **temperature extremes (bold type face)**. All room temperature limits are 100% production tested. All limits at **temperature extremes** are specified via correlation using standard Statistical Quality Control (SQC) methods. All limits are used to calculate Average Outgoing Quality Level (AOQL).
- (3) External components such as the catch diode, inductor, input and output capacitors, and voltage programming resistors can affect switching regulator performance. When the LM2672 is used as shown in Figure 22 and Figure 23 test circuits, system performance will be as specified by the system parameters section of the Electrical Characteristics.



LM2672-12 Electrical Characteristics

Symbol	Parameter	Conditions	Typ ⁽¹⁾	Min ⁽²⁾	Max ⁽²⁾	Units	
SYSTEM PARAMETERS Test Circuit Figure 22 ⁽³⁾							
V_{OUT}	Output Voltage	V_{IN} = 15V to 40V, I_{LOAD} = 20 mA to 1A	12	11.82/ 11.64	12.18/ 12.36	V	
η	Efficiency	V _{IN} = 24V, I _{LOAD} = 1A	94			%	

(1) Typical numbers are at 25°C and represent the most likely norm.

- (2) All limits specified at room temperature (standard type face) and at **temperature extremes (bold type face)**. All room temperature limits are 100% production tested. All limits at **temperature extremes** are specified via correlation using standard Statistical Quality Control (SQC) methods. All limits are used to calculate Average Outgoing Quality Level (AOQL).
- (3) External components such as the catch diode, inductor, input and output capacitors, and voltage programming resistors can affect switching regulator performance. When the LM2672 is used as shown in Figure 22 and Figure 23 test circuits, system performance will be as specified by the system parameters section of the Electrical Characteristics.

LM2672-ADJ Electrical Characteristics

Symbol	Parameter	Conditions	Typ ⁽¹⁾	Min ⁽²⁾	Max ⁽²⁾	Units
SYSTEM	PARAMETERS Test	Circuit Figure 23 ⁽³⁾	·			
V _{FB}	Feedback Voltage	V_{IN} = 8V to 40V, I_{LOAD} = 20 mA to 1A	1.210	1.192/ 1.174	1.228/ 1.246	V
		V _{OUT} Programmed for 5V				
		(see Circuit of Figure 23)				
V_{FB}	Feedback Voltage	V_{IN} = 6.5V to 40V, I_{LOAD} = 20 mA to 500 mA	1.210	1.192/ 1.174	1.228/ 1.246	V
		V _{OUT} Programmed for 5V				
		(see Circuit of Figure 23)				
η	Efficiency	V _{IN} = 12V, I _{LOAD} = 1A	90			%

(1) Typical numbers are at 25°C and represent the most likely norm.

- (2) All limits specified at room temperature (standard type face) and at **temperature extremes (bold type face)**. All room temperature limits are 100% production tested. All limits at **temperature extremes** are specified via correlation using standard Statistical Quality Control (SQC) methods. All limits are used to calculate Average Outgoing Quality Level (AOQL).
- (3) External components such as the catch diode, inductor, input and output capacitors, and voltage programming resistors can affect switching regulator performance. When the LM2672 is used as shown in Figure 22 and Figure 23 test circuits, system performance will be as specified by the system parameters section of the Electrical Characteristics.

All Output Voltage Versions

Specifications with standard type face are for $T_J = 25^{\circ}$ C, and those in **bold type face** apply over **full Operating Temperature Range**. Unless otherwise specified, $V_{IN} = 12V$ for the 3.3V, 5V, and Adjustable versions and $V_{IN} = 24V$ for the 12V version, and $V_{IN} = 100$ mA.

	Conditions	Тур	Min	Max	Units
PARAMETERS					
Quiescent Current	V _{FEEDBACK} = 8V	2.5		3.6	mA
	For 3.3V, 5.0V, and ADJ Versions				
	V _{FEEDBACK} = 15V	2.5			mA
	For 12V Versions				
Standby Quiescent Current	ON/OFF Pin = 0V	50		100/ 150	μA
Current Limit		1.55	1.25/ 1.2	2.1/ 2.2	Α
Output Leakage Current	$V_{IN} = 40V$, ON/\overline{OFF} Pin = $0V$	1		25	μA
	V _{SWITCH} = 0V				
	V _{SWITCH} = −1V, ON/ OFF Pin = 0V	6		15	mA
Switch On-Resistance	I _{SWITCH} = 1A	0.25		0.30/ 0.50	Ω
Oscillator Frequency	Measured at Switch Pin	260	225	275	kHz
Maximum Duty Cycle		95			%
Minimum Duty Cycle		0			%
Feedback Bias	V _{FEEDBACK} = 1.3V	85			nA
Current	ADJ Version Only				
	Standby Quiescent Current Current Limit Output Leakage Current Switch On-Resistance Oscillator Frequency Maximum Duty Cycle Minimum Duty Cycle Feedback Bias	For 3.3V, 5.0V, and ADJ Versions V_FEEDBACK = 15V For 12V Versions Standby Quiescent Current ON/OFF Pin = 0V Current Limit Output Leakage Current V_IN = 40V, ON/OFF Pin = 0V V_SWITCH = 0V V_SWITCH = -1V, ON/OFF Pin = 0V Switch On-Resistance I_SWITCH = 1A Oscillator Frequency Measured at Switch Pin Maximum Duty Cycle Minimum Duty Cycle Feedback Bias V_FEEDBACK = 1.3V	For 3.3V, 5.0V, and ADJ Versions	For 3.3V, 5.0V, and ADJ Versions V _{FEEDBACK} = 15V 2.5	For 3.3V, 5.0V, and ADJ Versions VFEEDBACK = 15V 2.5



All Output Voltage Versions (continued)

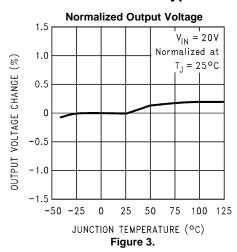
Specifications with standard type face are for $T_J = 25^{\circ}\text{C}$, and those in **bold type face** apply over **full Operating Temperature Range**. Unless otherwise specified, $V_{IN} = 12V$ for the 3.3V, 5V, and Adjustable versions and $V_{IN} = 24V$ for the 12V version, and $I_{I,OAD} = 100$ mA.

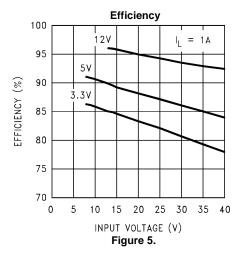
Symbol	Parameters	Conditions	Тур	Min	Max	Units
V _{S/D}	ON/OFF Pin		1.4	0.8	2.0	V
	Voltage Thesholds					
I _{S/D}	ON/OFF Pin Current	ON/OFF Pin = 0V	20	7	37	μA
F _{SYNC}	Synchronization Frequency	V _{SYNC} = 3.5V, 50% duty cycle	400			kHz
V _{SYNC}	Synchronization Threshold Voltage		1.4			V
V _{SS}	Soft-Start Voltage		0.63	0.53	0.73	V
I _{SS}	Soft-Start Current		4.5	1.5	6.9	μA
θ_{JA}	Thermal Resistance	PDIP Package, Junction to Ambient ⁽¹⁾	95			°C/W
		D Package, Junction to Ambient ⁽¹⁾	105			

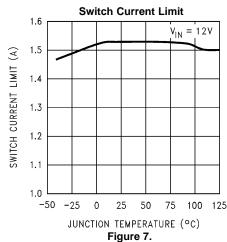
⁽¹⁾ Junction to ambient thermal resistance with approximately 1 square inch of printed circuit board copper surrounding the leads. Additional copper area will lower thermal resistance further. See Application Information section in the application note accompanying this datasheet and the thermal model in *LM267X Made Simple* version 6.0 software. The value θ_{J-A} for the WSON (NHN) package is specifically dependent on PCB trace area, trace material, and the number of layers and thermal vias. For improved thermal resistance and power dissipation for the WSON package, refer to Application Note AN-1187.

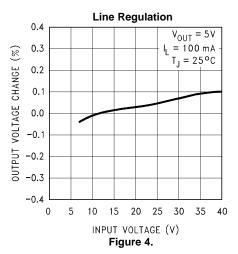


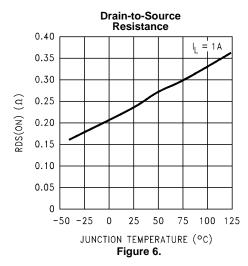
Typical Performance Characteristics

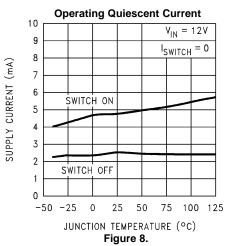
















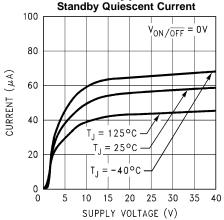
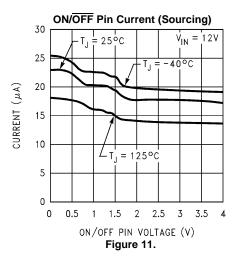
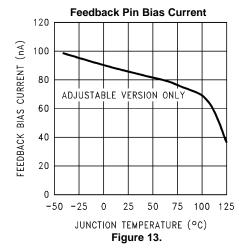
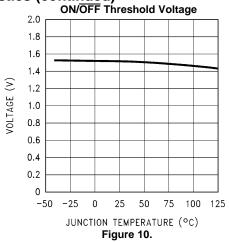
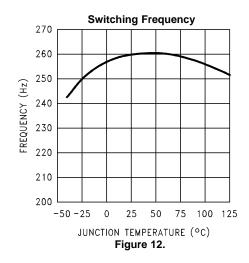


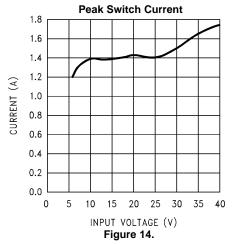
Figure 9.



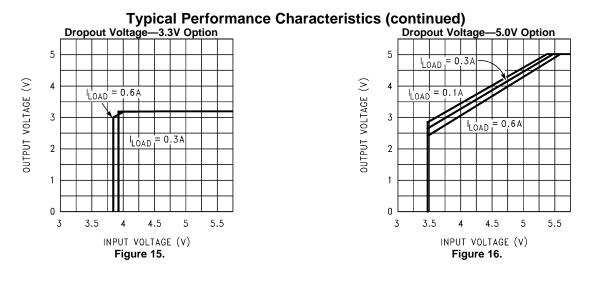


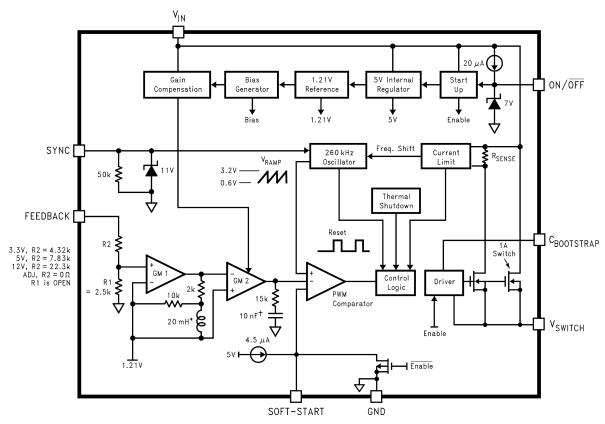












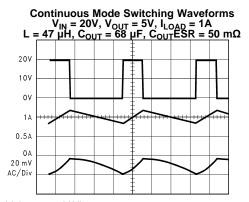
* Patent Number 5,514,947 † Patent Number 5,382,918

Figure 17. Block Diagram



Typical Performance Characteristics

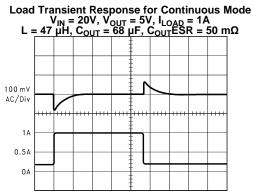
(Circuit of Figure 22)



A: V_{SW} Pin Voltage, 10 V/div. B: Inductor Current, 0.5 A/div

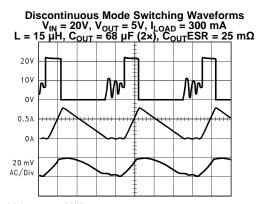
C: Output Ripple Voltage, 20 mV/div AC-Coupled

Figure 18. Horizontal Time Base: 1 µs/div



A: Output Voltage, 100 mV/div, AC-Coupled B: Load Current: 200 mA to 1A Load Pulse

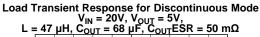
Figure 20. Horizontal Time Base: 50 μs/div

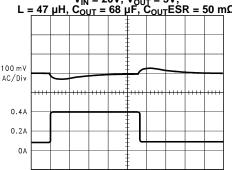


A: V_{SW} Pin Voltage, 10 V/div. B: Inductor Current, 0.5 A/div

C: Output Ripple Voltage, 20 mV/div AC-Coupled

Figure 19. Horizontal Time Base: 1 µs/div





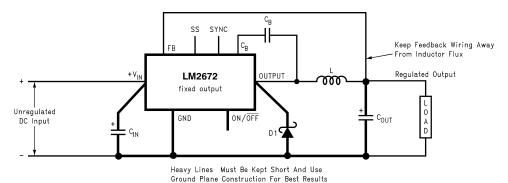
A: Output Voltage, 100 mV/div, AC-Coupled

B: Load Current: 100 mA to 300 mA Load Pulse

Figure 21. Horizontal Time Base: 200 μs/div



TEST CIRCUIT AND LAYOUT GUIDELINES



 C_{IN} - 22 μF , 50V Tantalum, Sprague "199D Series"

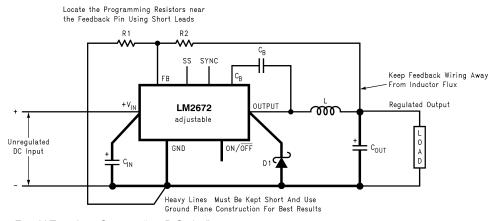
C_{OUT} - 47 μF, 25V Tantalum, Sprague "595D Series"

D1 - 3.3A, 50V Schottky Rectifier, IR 30WQ05F

L1 - 68 µH Sumida #RCR110D-680L

 C_B - 0.01 μF , 50V Ceramic

Figure 22. Standard Test Circuits and Layout Guides **Fixed Output Voltage Versions**



C_{IN} - 22 μF, 50V Tantalum, Sprague "199D Series"

C_{OUT} - 47 μF, 25V Tantalum, Sprague "595D Series"

D1 - 3.3A, 50V Schottky Rectifier, IR 30WQ05F

L1 - 68 µH Sumida #RCR110D-680L

R1 - 1.5 kΩ, 1%

 C_B - 0.01 μF , 50V Ceramic

For a 5V output, select R2 to be 4.75 k Ω , 1% $V_{OUT} = V_{REF} \left(1 + \frac{R_2}{R_1}\right)$

$$V_{OUT} = V_{REF} \left(1 + \frac{R_2}{R_1} \right)$$

where
$$V_{REF} = 1.21V$$
 $R_2 = R_1 \left(\frac{V_{OUT}}{V_{REF}} - 1 \right)$

Use a 1% resistor for best stability.

Figure 23. Standard Test Circuits and Layout Guides **Adjustable Output Voltage Versions**



Applications Hints

The LM2672 provides all of the active functions required for a step-down (buck) switching regulator. The internal power switch is a DMOS power MOSFET to provide power supply designs with high current capability, up to 1A, and highly efficient operation.

The LM2672 is part of the SIMPLE SWITCHER family of power converters. A complete design uses a minimum number of external components, which have been pre-determined from a variety of manufacturers. Using either this data sheet or TI's WEBENCH® design tool, a complete switching power supply can be designed quickly. Also, refer to the LM2670 data sheet for additional applications information.

SWITCH OUTPUT

This is the output of a power MOSFET switch connected directly to the input voltage. The switch provides energy to an inductor, an output capacitor and the load circuitry under control of an internal pulse-width-modulator (PWM). The PWM controller is internally clocked by a fixed 260kHz oscillator. In a standard step-down application the duty cycle (Time ON/Time OFF) of the power switch is proportional to the ratio of the power supply output voltage to the input voltage. The voltage on the V_{SW} pin cycles between V_{in} (switch ON) and below ground by the voltage drop of the external Schottky diode (switch OFF).

INPUT

The input voltage for the power supply is connected to the V_{IN} pin. In addition to providing energy to the load the input voltage also provides bias for the internal circuitry of the LM2672. For ensured performance the input voltage must be in the range of 6.5V to 40V. For best performance of the power supply the V_{IN} pin should always be bypassed with an input capacitor located close to this pin and GND.

C BOOST

A capacitor must be connected from the C_B pin to the V_{SW} pin. This capacitor boosts the gate drive to the internal MOSFET above V_{in} to fully turn it ON. This minimizes conduction losses in the power switch to maintain high efficiency. The recommended value for C Boost is $0.01\mu F$.

GROUND

This is the ground reference connection for all components in the power supply. In fast-switching, high-current applications such as those implemented with the LM2672, it is recommended that a broad ground plane be used to minimize signal coupling throughout the circuit

SYNC

This input allows control of the switching clock frequency. If left open-circuited the regulator will be switched at the internal oscillator frequency, typically 260 kHz. An external clock can be used to force the switching frequency and thereby control the output ripple frequency of the regulator. This capability provides for consistent filtering of the output ripple from system as well as precise frequency spectrum positioning of the ripple frequency which is often desired in communications and radio applications. This external frequency must be greater than the LM2672 internal oscillator frequency, which could be as high as 275 kHz, to prevent an erroneous reset of the internal ramp oscillator and PWM control of the power switch. The ramp oscillator is reset on the positive going edge of the sync input signal. It is recommended that the external TTL or CMOS compatible clock (between 0V and a level greater than 3V) be ac coupled to the SYNC pin through a 100pF capacitor and a $1K\Omega$ resistor to ground.

When the SYNC function is used, current limit frequency foldback is not active. Therefore, the device may not be fully protected against extreme output short circuit conditions.

FEEDBACK

This is the input to a two-stage high gain amplifier, which drives the PWM controller. Connect the FB pin directly to the output for proper regulation. For the fixed output devices (3.3V, 5V and 12V outputs), a direct wire connection to the output is all that is required as internal gain setting resistors are provided inside the LM2672. For the adjustable output version two external resistors are required to set the dc output voltage. For stable operation of the power supply it is important to prevent coupling of any inductor flux to the feedback input.



ON/OFF

This input provides an electrical ON/OFF control of the power supply. Connecting this pin to ground or to any voltage less than 0.8V will completely turn OFF the regulator. The current drain from the input supply when OFF is only 50µA. The ON/OFF input has an internal pull-up current source of approximately 20µA and a protection clamp zener diode of 7V to ground. When electrically driving the ON/OFF pin the high voltage level for the ON condition should not exceed the 6V absolute maximum limit. When ON/OFF control is not required this pin should be left open.

DAP (WSON PACKAGE)

The Die Attach Pad (DAP) can and should be connected to the PCB Ground plane/island. For CAD and assembly guidelines refer to Application Note SNAO401 at http://www.ti.com/lit/an/snoa401/snoa401.pdf.

LM2672 Series Buck Regulator Design Procedure (Fixed Output)

PROCEDURE (Fixed Output Voltage Version)	EXAMPLE (Fixed Output Voltage Version)
To simplify the buck regulator design procedure, Texas Instruments is making available computer design software to be used with the SIMPLE SWITCHER line of switching regulators. LM267X Made Simple version 6.0 is available on Windows [®] 3.1, NT, or 95 operating systems.	
Given:	Given:
V _{OUT} = Regulated Output Voltage (3.3V, 5V, or 12V)	V _{OUT} = 5V
V _{IN} (max) = Maximum DC Input Voltage	$V_{IN}(max) = 12V$
I _{LOAD} (max) = Maximum Load Current	$I_{LOAD}(max) = 1A$
1. Inductor Selection (L1) A. Select the correct inductor value selection guide from Figure 24 and Figure 25 or Figure 26 (output voltages of 3.3V, 5V, or 12V respectively). For all other voltages, see the design procedure for the adjustable version.	Inductor Selection (L1) A. Use the inductor selection guide for the 5V version shown in Figure 25.
B. From the inductor value selection guide, identify the inductance region intersected by the Maximum Input Voltage line and the Maximum Load Current line. Each region is identified by an inductance value and an inductor code (LXX).	B. From the inductor value selection guide shown in Figure 25, the inductance region intersected by the 12V horizontal line and the 1A vertical line is 33 μ H, and the inductor code is L23.
C. Select an appropriate inductor from the four manufacturer's part numbers listed in Table 1. Each manufacturer makes a different style of inductor to allow flexibility in meeting various design requirements. Listed below are some of the differentiating characteristics of each manufacturer's inductors:	C. The inductance value required is 33 µH. From the table in Table 1, go to the L23 line and choose an inductor part number from any of the four manufacturers shown. (In most instances, both through hole and surface mount inductors are available.)
Schott: ferrite EP core inductors; these have very low leakage magnetic fields to reduce electro-magnetic interference (EMI) and are the lowest power loss inductors	
Renco: ferrite stick core inductors; benefits are typically lowest cost inductors and can withstand E•T and transient peak currents above rated value. Be aware that these inductors have an external magnetic field which may generate more EMI than other types of inductors.	
Pulse: powered iron toroid core inductors; these can also be low cost and can withstand larger than normal E•T and transient peak currents. Toroid inductors have low EMI.	
Coilcraft: ferrite drum core inductors; these are the smallest physical size inductors, available only as SMT components. Be aware that these inductors also generate EMI—but less than stick inductors.	
Complete specifications for these inductors are available from the respective manufacturers. A table listing the manufacturers' phone numbers is located in Table 2.	

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PROCEDURE (Fixed Output Voltage Version)

2. Output Capacitor Selection (Cour)

A. Select an output capacitor from the output capacitor table in Table 3. Using the output voltage and the inductance value found in the inductor selection guide, step 1, locate the appropriate capacitor value and voltage rating.

The capacitor list contains through-hole electrolytic capacitors from four different capacitor manufacturers and surface mount tantalum capacitors from two different capacitor manufacturers. It is recommended that both the manufacturers and the manufacturer's series that are listed in the table be used. A table listing the manufacturers' phone numbers is located in Table 4.

3. Catch Diode Selection (D1)

A. In normal operation, the average current of the catch diode is the load current times the catch diode duty cycle, 1-D (D is the switch duty cycle, which is approximately the output voltage divided by the input voltage). The largest value of the catch diode average current occurs at the maximum load current and maximum input voltage (minimum D). For normal operation, the catch diode current rating must be at least 1.3 times greater than its maximum average current. However, if the power supply design must withstand a continuous output short, the diode should have a current rating equal to the maximum current limit of the LM2672. The most stressful condition for this diode is a shorted output condition.

- **B.** The reverse voltage rating of the diode should be at least 1.25 times the maximum input voltage.
- **C.** Because of their fast switching speed and low forward voltage drop, Schottky diodes provide the best performance and efficiency. This Schottky diode must be located close to the LM2672 using short leads and short printed circuit traces.

4. Input Capacitor (CIN)

A low ESR aluminum or tantalum bypass capacitor is needed between the input pin and ground to prevent large voltage transients from appearing at the input. This capacitor should be located close to the IC using short leads. In addition, the RMS current rating of the input capacitor should be selected to be at least 1/2 the DC load current. The capacitor manufacturer data sheet must be checked to assure that this current rating is not exceeded. The curves shown in Figure 28 show typical RMS current ratings for several different aluminum electrolytic capacitor values. A parallel connection of two or more capacitors may be required to increase the total minimum RMS current rating to suit the application requirements. For an aluminum electrolytic capacitor, the voltage rating should be at least 1.25 times the maximum input voltage. Caution must be exercised if solid tantalum capacitors are used. The tantalum capacitor voltage rating should be twice the maximum input voltage. The tables in Table 7 show the recommended application voltage for AVX TPS and Sprague 594D tantalum capacitors. It is also recommended that they be surge current tested by the manufacturer. The TPS series available from AVX, and the 593D and 594D series from Sprague are all surge current tested. Another approach to minimize the surge current stresses on the input capacitor is to add a small inductor in series with the input supply line. Use caution when using ceramic capacitors for input bypassing,

5. Boost Capacitor (C_B)

This capacitor develops the necessary voltage to turn the switch gate on fully. All applications should use a 0.01 μF , 50V ceramic capacitor.

because it may cause severe ringing at the V_{IN} pin.

EXAMPLE (Fixed Output Voltage Version)

2. Output Capacitor Selection (Cour)

A. Use the 5.0V section in the output capacitor table in Table 3. Choose a capacitor value and voltage rating from the line that contains the inductance value of 33 μ H. The capacitance and voltage rating values corresponding to the 33 μ H

Surface Mount:

 $68~\mu F/10V~$ Sprague 594D Series. $100~\mu F/10V~$ AVX TPS Series.

Through Hole:

68 μF/10V Sanyo OS-CON SA Series. 220 μF/35V Sanyo MV-GX Series. 220 μF/35V Nichicon PL Series. 220 μF/35V Panasonic HFQ Series.

3. Catch Diode Selection (D1)

A. Refer to the table shown in Table 5. In this example, a 1A, 20V Schottky diode will provide the best performance. If the circuit must withstand a continuous shorted output, a higher current Schottky diode is recommended.

4. Input Capacitor (CIN)

The important parameters for the input capacitor are the input voltage rating and the RMS current rating. With a maximum input voltage of 12V, an aluminum electrolytic capacitor with a voltage rating greater than 15V (1.25 × V_{IN}) would be needed. The next higher capacitor voltage rating is 16V.

The RMS current rating requirement for the input capacitor in a buck regulator is approximately ½ the DC load current. In this example, with a 1A load, a capacitor with a RMS current rating of at least 500 mA is needed. The curves shown in Figure 28 can be used to select an appropriate input capacitor. From the curves, locate the 16V line and note which capacitor values have RMS current ratings greater than 500 mA

For a through hole design, a 330 µF/16V electrolytic capacitor (Panasonic HFQ series, Nichicon PL, Sanyo MV-GX series or equivalent) would be adequate. Other types or other manufacturers' capacitors can be used provided the RMS ripple current ratings are adequate. Additionally, for a complete surface mount design, electrolytic capacitors such as the Sanyo CV-C or CV-BS and the Nichicon WF or UR and the NIC Components NACZ series could be considered.

For surface mount designs, solid tantalum capacitors can be used, but caution must be exercised with regard to the capacitor surge current rating and voltage rating. In this example, checking Table 7, and the Sprague 594D series datasheet, a Sprague 594D 15 $\mu\text{F},$ 25V capacitor is adequate.

5. Boost Capacitor (C_B)

For this application, and all applications, use a 0.01 μF , 50V ceramic capacitor.



PROCEDURE (Fixed Output Voltage Version)

6. Soft-Start Capacitor (CSS - optional)

This capacitor controls the rate at which the device starts up. The formula for the soft-start capacitor CSS is:

$$C_{SS} \approx (I_{SS} \cdot t_{SS}) / [V_{SSTH} + 2.6V \cdot (\frac{V_{OUT} + V_{SCHOTTKY}}{V_{IN}})]$$
 (1)

where:

I_{SS} = Soft-Start Current: 4.5 μA typical.

t_{SS} = Soft-Start Time: Selected.

 \bar{V}_{SSTH} = Soft-Start Threshold Voltage :0.63V typical.

V_{OUT} = Output Voltage: Selected.

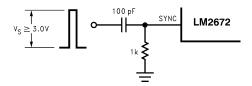
 V_{SCHOTTKY} = Schottky Diode Voltage Drop: 0.4V typical. V_{IN} = Input Voltage: Selected.

If this feature is not desired, leave this pin open. With certain softstart capacitor values and operating conditions, the LM2672 can exhibit an overshoot on the output voltage during turn on. Especially when starting up into no load or low load, the softstart function may not be effective in preventing a larger voltage overshoot on the output. With larger loads or lower input voltages during startup this effect is minimized. In particular, avoid using softstart capacitors between 0.033µF and 1µF.

7. Frequency Synchronization (optional)

The LM2672 (oscillator) can be synchronized to run with an external oscillator, using the sync pin (pin 3). By doing so, the LM2672 can be operated at higher frequencies than the standard frequency of 260 kHz. This allows for a reduction in the size of the inductor and output capacitor.

As shown in the drawing below, a signal applied to a RC filter at the sync pin causes the device to synchronize to the frequency of that signal. For a signal with a peak-to-peak amplitude of 3V or greater, a 1 k Ω resistor and a 100 pF capacitor are suitable values.



EXAMPLE (Fixed Output Voltage Version)

6. Soft-Start Capacitor (C_{SS} - optional)

For this application, selecting a start-up time of 10 ms and using the formula for C_{SS} results in a value of:

$$C_{SS} \approx (4.5 \ \mu\text{A} \cdot 10 \ \text{ms}) / [0.63\text{V} + 2.6\text{V} \cdot (\frac{5\text{V} + 0.4\text{V}}{12\text{V}})]$$

= 25 nF $\approx 0.022 \ \mu\text{F}$. (2)

7. Frequency Synchronization (optional)

For all applications, use a 1 k Ω resistor and a 100 pF capacitor for the RC filter.

Inductor Value Selection Guides

(For Continuous Mode Operation)

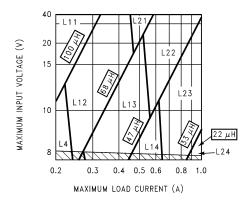


Figure 24. LM2672-3.3

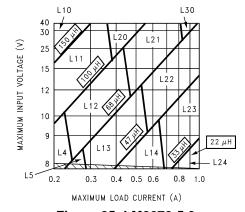


Figure 25. LM2672-5.0



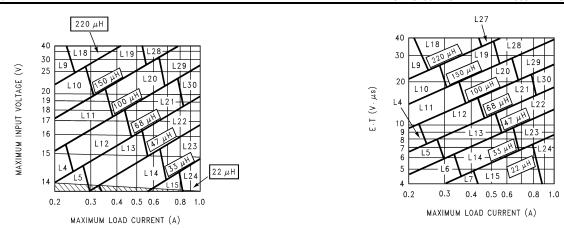


Figure 26. LM2672-12

Figure 27. LM2672-ADJ

Table 1. Inductor Manufacturers' Part Numbers

Ind.			Scl	nott	Renco			ngineering	Coilcraft
Ref.	Inductance (µH)	Current (A)	Through	Surface	Through	Surface	Through	Surface	Surface
Desg.	(μ11)	(A)	Hole	Mount	Hole	Mount	Hole	Mount	Mount
L4	68	0.32	67143940	67144310	RL-1284-68-43	RL1500-68	PE-53804	PE-53804-S	DO1608-683
L5	47	0.37	67148310	67148420	RL-1284-47-43	RL1500-47	PE-53805	PE-53805-S	DO1608-473
L6	33	0.44	67148320	67148430	RL-1284-33-43	RL1500-33	PE-53806	PE-53806-S	DO1608-333
L7	22	0.52	67148330	67148440	RL-1284-22-43	RL1500-22	PE-53807	PE-53807-S	DO1608-223
L9	220	0.32	67143960	67144330	RL-5470-3	RL1500-220	PE-53809	PE-53809-S	DO3308-224
L10	150	0.39	67143970	67144340	RL-5470-4	RL1500-150	PE-53810	PE-53810-S	DO3308-154
L11	100	0.48	67143980	67144350	RL-5470-5	RL1500-100	PE-53811	PE-53811-S	DO3308-104
L12	68	0.58	67143990	67144360	RL-5470-6	RL1500-68	PE-53812	PE-53812-S	DO3308-683
L13	47	0.70	67144000	67144380	RL-5470-7	RL1500-47	PE-53813	PE-53813-S	DO3308-473
L14	33	0.83	67148340	67148450	RL-1284-33-43	RL1500-33	PE-53814	PE-53814-S	DO3308-333
L15	22	0.99	67148350	67148460	RL-1284-22-43	RL1500-22	PE-53815	PE-53815-S	DO3308-223
L18	220	0.55	67144040	67144420	RL-5471-2	RL1500-220	PE-53818	PE-53818-S	DO3316-224
L19	150	0.66	67144050	67144430	RL-5471-3	RL1500-150	PE-53819	PE-53819-S	DO3316-154
L20	100	0.82	67144060	67144440	RL-5471-4	RL1500-100	PE-53820	PE-53820-S	DO3316-104
L21	68	0.99	67144070	67144450	RL-5471-5	RL1500-68	PE-53821	PE-53821-S	DO3316-683
L22	47	1.17	67144080	67144460	RL-5471-6		PE-53822	PE-53822-S	DO3316-473
L23	33	1.40	67144090	67144470	RL-5471-7		PE-53823	PE-53823-S	DO3316-333
L24	22	1.70	67148370	67148480	RL-1283-22-43	_	PE-53824	PE-53824-S	DO3316-223
L27	220	1.00	67144110	67144490	RL-5471-2		PE-53827	PE-53827-S	DO5022P-224
L28	150	1.20	67144120	67144500	RL-5471-3		PE-53828	PE-53828-S	DO5022P-154
L29	100	1.47	67144130	67144510	RL-5471-4	_	PE-53829	PE-53829-S	DO5022P-104
L30	68	1.78	67144140	67144520	RL-5471-5	_	PE-53830	PE-53830-S	DO5022P-683



Table 2. Inductor Manufacturers' Phone Numbers

Coilcraft Inc.	Phone	(800) 322-2645	
	FAX	(708) 639-1469	
Coilcraft Inc., Europe	Phone	+44 1236 730 595	
	FAX	+44 1236 730 627	
Pulse Engineering Inc.	Phone	(619) 674-8100	
	FAX	(619) 674-8262	
Pulse Engineering Inc.,	Phone	+353 93 24 107	
Europe	FAX	+353 93 24 459	
Renco Electronics Inc.	Phone	(800) 645-5828	
	FAX	(516) 586-5562	
Schott Corp.	Phone	(612) 475-1173	
	FAX	(612) 475-1786	

Table 3. Output Capacitor Table

		Output Capacitor						
Output		Surface Mount						
Voltage	Inductance (µH)	Sprague	AVX TPS	Sanyo OS-CON	Sanyo MV-GX	Nichicon	Panasonic	
(V)	(μπ)	594D Series	Series	SA Series	Series	PL Series	HFQ Series	
		(μF/V)	(μF/V)	(μF/V)	(μF/V)	PL Series (μF/V) 330/35 220/35 150/35 120/35 120/35 120/35 120/35 150/35 120/35 120/35 120/35 120/35 120/35 120/35 120/35 120/35 120/35 120/35 120/35	(μF/V)	
	22	120/6.3	100/10	100/10	330/35	330/35	330/35	
	33	120/6.3	100/10	68/10	220/35	220/35	220/35	
3.3	47	68/10	100/10	68/10	150/35	150/35	150/35	
3.3	68	120/6.3	100/10	100/10	120/35	120/35	120/35	
	100	120/6.3	100/10	100/10	120/35	120/35	120/35	
	150	120/6.3	100/10	100/10	120/35	120/35	120/35	
	22	100/16	100/10	100/10	330/35	330/35	330/35	
	33	68/10	10010	68/10	220/35	220/35	220/35	
5 0	47	68/10	100/10	68/10	150/35	150/35	150/35	
5.0	68	100/16	100/10	100/10	120/35	120/35	120/35	
	100	100/16	100/10	100/10	120/35	120/35	120/35	
	150	100/16	100/10	100/10	120/35	120/35	120/35	
	22	120/20	(2x) 68/20	68/20	330/35	330/35	330/35	
	33	68/25	68/20	68/20	220/35	220/35	220/35	
	47	47/20	68/20	47/20	150/35	150/35	150/35	
12	68	47/20	68/20	47/20	120/35	120/35	120/35	
	100	47/20	68/20	47/20	120/35	120/35	120/35	
	150	47/20	68/20	47/20	120/35	120/35	120/35	
	220	47/20	68/20	47/20	120/35	120/35	120/35	



Table 4. Capacitor Manufacturers' Phone Numbers

Nichican Com	Phone	(847) 843-7500
Nichicon Corp.	FAX	(847) 843-2798
Panasonic	Phone	(714) 373-7857
Pallasonic	FAX	(714) 373-7102
AVV Core	Phone	(803) 448-9411
AVX Corp.	FAX	(803) 448-1943
Care and Michael	Phone	(207) 324-4140
Sprague/Vishay	FAX	(207) 324-7223
Sanyo Corp.	Phone	(619) 661-6322
	FAX	(619) 661-1055

Table 5. Schottky Diode Selection Table

	1A Dio	odes	3A Di	odes	
V _R	Surface	Through	Surface	Through	
	Mount	Hole	Mount	Hole	
20V	SK12	1N5817	SK32	1N5820	
	B120	SR102		SR302	
30V	SK13	1N5818	SK33	1N5821	
	B130	11DQ03	30WQ03F	31DQ03	
	MBRS130	SR103			
40V	SK14	1N5819	SK34	1N5822	
	B140	11DQ04	30BQ040	MBR340	
	MBRS140	SR104	30WQ04F	31DQ04	
	10BQ040		MBRS340	SR304	
	10MQ040		MBRD340		
	15MQ040				
50V	SK15	MBR150	SK35	MBR350	
	B150	11DQ05	30WQ05F	31DQ05	
	10BQ050	SR105		SR305	

Table 6. Diode Manufacturers' Phone Numbers

International Rectifier Corp.	Phone	(310) 322-3331	
	FAX	(310) 322-3332	
Motorola, Inc.	Phone	(800) 521-6274	
	FAX	(602) 244-6609	
General Instruments Corp.	Phone	(516) 847-3000	
	FAX	(516) 847-3236	
Diodes, Inc.	Phone	(805) 446-4800	
	FAX	(805) 446-4850	



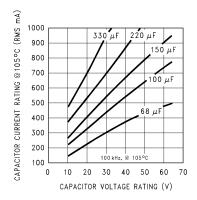


Figure 28. RMS Current Ratings for Low ESR Electrolytic Capacitors (Typical)

Table 7. Recommended Application Voltage for AVX TPS and Sprague 594D Tantalum Chip Capacitors Derated for 85°C.

Recommended Application Voltage	Voltage Rating
+	85°C Rating
3.3	6.3
5	10
10	20
12	25
15	35

Table 8. Sprague 594D

Recommended Application Voltage	Voltage Rating
+	85°C Rating
2.5	4
3.3	6.3
5	10
8	16
12	20
18	25
24	35
29	50



LM2672 Series Buck Regulator Design Procedure (Adjustable Output)

PROCEDURE (Adjustable Output Voltage Version)

To simplify the buck regulator design procedure, Texas Instruments is making available computer design software to be used with the SIMPLE SWITCHERline of switching regulators. **LM267X Made Simple version 6.0 is available on**Windows 3.1, NT, or 95 operating systems.

Given:

V_{OUT} = Regulated Output Voltage

V_{IN}(max) = Maximum Input Voltage

I_{LOAD}(max) = Maximum Load Current

F = Switching Frequency (Fixed at a nominal 260 kHz).

1. Programming Output Voltage (Selecting R₁ and R₂, as shown in Figure 23)

Use the following formula to select the appropriate resistor values.

$$V_{OUT} = V_{REF} \left(1 + \frac{R_2}{R_1} \right)_{\text{where } V_{REF}} = 1.21V$$
 (3)

Select a value for R_1 between 240Ω and $1.5~k\Omega$. The lower resistor values minimize noise pickup in the sensitive feedback pin. (For the lowest temperature coefficient and the best stability with time, use 1% metal film resistors.)

$$R_2 = R_1 \left(\frac{V_{OUT}}{V_{REF}} - 1 \right) \tag{5}$$

2. Inductor Selection (L1)

A. Calculate the inductor Volt • microsecond constant E • T (V • μs), from the following formula:

E • T =
$$(V_{IN(MAX)} - V_{OUT} - V_{SAT}) \cdot \frac{V_{OUT} + V_D}{V_{IN(MAX)} - V_{SAT} + V_D} \cdot \frac{1000}{260} (V \cdot \mu s)$$
(6)

where V_{SAT} =internal switch saturation voltage=0.25V and V_D = diode forward voltage drop = 0.5V

- **B.** Use the E T value from the previous formula and match it with the E T number on the vertical axis of the Inductor Value Selection Guide shown in Figure 27.
- C. On the horizontal axis, select the maximum load current.
- **D.** Identify the inductance region intersected by the E T value and the Maximum Load Current value. Each region is identified by an inductance value and an inductor code (LXX).
- **E.** Select an appropriate inductor from the four manufacturer's part numbers listed in Table 1. For information on the different types of inductors, see the inductor selection in the fixed output voltage design procedure.

3. Output Capacitor Selection (COUT)

A. Select an output capacitor from the capacitor code selection guide in Table 9. Using the inductance value found in the inductor selection guide, step 1, locate the appropriate capacitor code corresponding to the desired output voltage.

EXAMPLE (Adjustable Output Voltage Version)

Given:

 $V_{OUT} = 20V$

 $V_{IN}(max) = 28V$

 $I_{LOAD}(max) = 1A$

F = Switching Frequency (Fixed at a nominal 260 kHz).

1. Programming Output Voltage (Selecting $\ensuremath{R_1}$ and $\ensuremath{R_2},$ as shown in Figure 23)

Select R_1 to be 1 k Ω , 1%. Solve for R_2 .

$$R_2 = R_1 \left(\frac{V_{OUT}}{V_{REF}} - 1 \right) = 1 k\Omega \left(\frac{20V}{1.23V} - 1 \right)$$
 (4)

 R_2 = 1 k Ω (16.53 $^-$ 1) = 15.53 k $\Omega,$ closest 1% value is 15.4 k $\Omega.$ R_2 = 15.4 k $\Omega.$

2. Inductor Selection (L1)

A. Calculate the inductor Volt • microsecond constant (E • T),

E • T =
$$(28 - 20 - 0.25) \cdot \frac{20 + 0.5}{28 - 0.25 + 0.5} \cdot \frac{1000}{260} \quad (V \cdot \mu s)$$

E • T = $(7.75) \cdot \frac{20.5}{28.25} \cdot 3.85 \quad (V \cdot \mu s) = 21.6 \quad (V \cdot \mu s)$ (7)

B. E • T = 21.6 (V •
$$\mu$$
s)

- **C.** $I_{LOAD}(max) = 1A$
- **D.** From the inductor value selection guide shown in Figure 27, the inductance region intersected by the 21.6 (V \bullet µs) horizontal line and the 1A vertical line is 68 µH, and the inductor code is L30.
- **E.** From the table in Table 1, locate line L30, and select an inductor part number from the list of manufacturers' part numbers.

3. Output Capacitor Selection (Cout)

A. Use the appropriate row of the capacitor code selection guide, in Table 9. For this example, use the 15–20V row. The capacitor code corresponding to an inductance of 68 μ H is C20.



PROCEDURE (Adjustable Output Voltage Version)

B. Select an appropriate capacitor value and voltage rating, using the capacitor code, from the output capacitor selection table in Table 10. There are two solid tantalum (surface mount) capacitor manufacturers and four electrolytic (through hole) capacitor manufacturers to choose from. It is recommended that both the manufacturers and the manufacturer's series that are listed in the table be used. A table listing the manufacturers' phone numbers is located in Table 4.

4. Catch Diode Selection (D1)

A. In normal operation, the average current of the catch diode is the load current times the catch diode duty cycle, 1-D (D is the switch duty cycle, which is approximately V_{OUT}/V_{IN}). The largest value of the catch diode average current occurs at the maximum input voltage (minimum D). For normal operation, the catch diode current rating must be at least 1.3 times greater than its maximum average current. However, if the power supply design must withstand a continuous output short, the diode should have a current rating greater than the maximum current limit of the LM2672. The most stressful condition for this diode is a shorted output condition.

- B. The reverse voltage rating of the diode should be at least 1.25 times the maximum input voltage.
- C. Because of their fast switching speed and low forward voltage drop, Schottky diodes provide the best performance and efficiency. The Schottky diode must be located close to the LM2672 using short leads and short printed circuit traces.

5. Input Capacitor (CIN)

A low ESR aluminum or tantalum bypass capacitor is needed between the input pin and ground to prevent large voltage transients from appearing at the input. This capacitor should be located close to the IC using short leads. In addition, the RMS current rating of the input capacitor should be selected to be at least ½ the DC load current. The capacitor manufacturer data sheet must be checked to assure that this current rating is not exceeded. The curves shown in Figure 28 show typical RMS current ratings for several different aluminum electrolytic capacitor values. A parallel connection of two or more capacitors may be required to increase the total minimum RMS current rating to suit the application requirements. For an aluminum electrolytic capacitor, the voltage rating should be at least 1.25 times the maximum input voltage. Caution must be exercised if solid tantalum capacitors are used. The tantalum capacitor voltage rating should be twice the maximum input voltage. The tables in Table 7 show the recommended application voltage for AVX TPS and Sprague 594D tantalum capacitors. It is also recommended that they be surge current tested by the manufacturer. The TPS series available from AVX, and the 593D and 594D series from Sprague are all surge current tested. Another approach to minimize the surge current stresses on the input capacitor is to add a small inductor in series with the input supply line. Use caution when using ceramic capacitors for input bypassing, because it may cause severe ringing at the V_{IN} pin.

6. Boost Capacitor (C_B)

This capacitor develops the necessary voltage to turn the switch gate on fully. All applications should use a 0.01 µF, 50V ceramic capacitor.

If the soft-start and frequency synchronization features are desired, look at steps 6 and 7 in the fixed output design procedure.

EXAMPLE (Adjustable Output Voltage Version)

B. From the output capacitor selection table in Table 10, choose a capacitor value (and voltage rating) that intersects the capacitor code(s) selected in section A, C20 (Table 10).

The capacitance and voltage rating values corresponding to the capacitor code C20 are the:

Surface Mount:

33 μF/25V Sprague 594D Series. 33 μF/25V AVX TPS Series.

Through Hole:

33 µF/25V Sanyo OS-CON SC Series.

120 μF/35V Sanyo MV-GX Series.

120 µF/35V Nichicon PL Series.

120 µF/35V Panasonic HFQ Series.

Other manufacturers or other types of capacitors may also be used, provided the capacitor specifications (especially the 100 kHz ESR) closely match the characteristics of the capacitors listed in the output capacitor table. Refer to the capacitor manufacturers' data sheet for this information.

4. Catch Diode Selection (D1)

A. Refer to the table shown in Table 5. Schottky diodes provide the best performance, and in this example a 1A, 40V Schottky diode would be a good choice. If the circuit must withstand a continuous shorted output, a higher current (at least 2.2A) Schottky diode is recommended.

5. Input Capacitor (CIN)

The important parameters for the input capacitor are the input voltage rating and the RMS current rating. With a maximum input voltage of 28V, an aluminum electrolytic capacitor with a voltage rating of at least 35V (1.25 \times V_{IN}) would be needed.

The RMS current rating requirement for the input capacitor in a buck regulator is approximately ½ the DC load current. In this example, with a 1A load, a capacitor with a RMS current rating of at least 500 mA is needed. The curves shown in Figure 28 can be used to select an appropriate input capacitor. From the curves, locate the 35V line and note which capacitor values have RMS current ratings greater

For a through hole design, a 330 µF/35V electrolytic capacitor (Panasonic HFQ series, Nichicon PL, Sanyo MV-GX series or equivalent) would be adequate. Other types or other manufacturers' capacitors can be used provided the RMS ripple current ratings are adequate. Additionally, for a complete surface mount design, electrolytic capacitors such as the Sanyo CV-C or CV-BS and the Nichicon WF or UR and the NIC Components NACZ series could be considered.

For surface mount designs, solid tantalum capacitors can be used, but caution must be exercised with regard to the capacitor surge current rating and voltage rating. In this example, checking Table 7, and the Sprague 594D series datasheet, a Sprague 594D 15 µF, 50V capacitor is adequate.

6. Boost Capacitor (CB)

For this application, and all applications, use a 0.01 µF, 50V ceramic capacitor.

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Table 9. Capacitor Code Selection Guide

Case	Output		Inductance (μH)							
Style ⁽¹⁾	Voltage (V)	22	33	47	68	100	150	220		
SM and TH	1.21-2.50	_	_	_	_	C1	C2	C3		
SM and TH	2.50-3.75	_	_	_	C1	C2	C3	C3		
SM and TH	3.75-5.0	_	_	C4	C5	C6	C6	C6		
SM and TH	5.0-6.25	_	C4	C7	C6	C6	C6	C6		
SM and TH	6.25–7.5	C8	C4	C7	C6	C6	C6	C6		
SM and TH	7.5–10.0	C9	C10	C11	C12	C13	C13	C13		
SM and TH	10.0–12.5	C14	C11	C12	C12	C13	C13	C13		
SM and TH	12.5–15.0	C15	C16	C17	C17	C17	C17	C17		
SM and TH	15.0–20.0	C18	C19	C20	C20	C20	C20	C20		
SM and TH	20.0–30.0	C21	C22	C22	C22	C22	C22	C22		
TH	30.0–37.0	C23	C24	C24	C25	C25	C25	C25		

⁽¹⁾ SM - Surface Mount, TH - Through Hole

Table 10. Output Capacitor Selection Table

Output Capacitor									
Сар.	Surface	Mount		Through	Hole				
Сар. Ref.	Sprague	AVX TPS	Sanyo OS-CON	Sanyo MV-GX	Nichicon	Panasonic			
Desg.	594D Series	Series	SA Series	Series	PL Series	HFQ Series			
#	(μF/V)	(μF/V)	(μF/V)	(μF/V)	(μF/V)	(μF/V)			
C1	120/6.3	100/10	100/10	220/35	220/35	220/35			
C2	120/6.3	100/10	100/10	150/35	150/35	150/35			
C3	120/6.3	100/10	100/35	120/35	120/35	120/35			
C4	68/10	100/10	68/10	220/35	220/35	220/35			
C5	100/16	100/10	100/10	150/35	150/35	150/35			
C6	100/16	100/10	100/10	120/35	120/35	120/35			
C7	68/10	100/10	68/10	150/35	150/35	150/35			
C8	100/16	100/10	100/10	330/35	330/35	330/35			
C9	100/16	100/16	100/16	330/35	330/35	330/35			
C10	100/16	100/16	68/16	220/35	220/35	220/35			
C11	100/16	100/16	68/16	150/35	150/35	150/35			
C12	100/16	100/16	68/16	120/35	120/35	120/35			
C13	100/16	100/16	100/16	120/35	120/35	120/35			
C14	100/16	100/16	100/16	220/35	220/35	220/35			
C15	47/20	68/20	47/20	220/35	220/35	220/35			
C16	47/20	68/20	47/20	150/35	150/35	150/35			
C17	47/20	68/20	47/20	120/35	120/35	120/35			
C18	68/25	(2×) 33/25	47/25 ⁽¹⁾	220/35	220/35	220/35			
C19	33/25	33/25	33/25 ⁽¹⁾	150/35	150/35	150/35			
C20	33/25	33/25	33/25 ⁽¹⁾	120/35	120/35	120/35			
C21	33/35	(2×) 22/25	See ⁽²⁾	150/35	150/35	150/35			
C22	33/35	22/35	See ⁽²⁾	120/35	120/35	120/35			
C23	See ⁽²⁾	See ⁽²⁾	See ⁽²⁾	220/50	100/50	120/50			
C24	See ⁽²⁾	See ⁽²⁾	See ⁽²⁾	150/50	100/50	120/50			
C25	See ⁽²⁾	See ⁽²⁾	See ⁽²⁾	150/50	82/50	82/50			

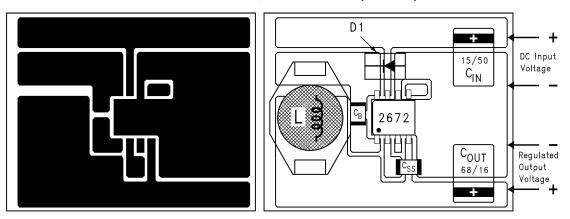
¹⁾ The SC series of Os-Con capacitors (others are SA series)

⁽²⁾ The voltage ratings of the surface mount tantalum chip and Os-Con capacitors are too low to work at these voltages.



Application Information

TYPICAL SURFACE MOUNT PC BOARD LAYOUT, FIXD OUTPUT (4X SIZE)



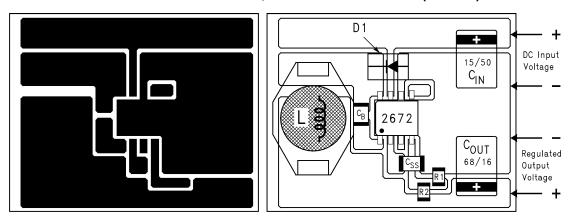
 C_{IN} - 15 μ F, 50V, Solid Tantalum Sprague, "594D series" C_{OUT} - 68 μ F, 16V, Solid Tantalum Sprague, "594D series"

D1 - 1A, 40V Schottky Rectifier, Surface Mount

L1 - 33 µH, L23, Coilcraft DO3316

 C_B - 0.01 μF , 50V, Ceramic

TYPICAL SURFACE MOUNT PC BOARD LAYOUT, ADJUSTABLE OUTPUT (4X SIZE)



 C_{IN} - 15 μ F, 50V, Solid Tantalum Sprague, "594D series" C_{OUT} - 33 μ F, 25V, Solid Tantalum Sprague, "594D series"

D1 - 1A, 40V Schottky Rectifier, Surface Mount

L1 - 68 µH, L30, Coilcraft DO3316

C_B - 0.01 μF, 50V, Ceramic

R1 - 1k, 1%

R2 - Use formula in Design Procedure

Figure 29. PC Board Layout

Layout is very important in switching regulator designs. Rapidly switching currents associated with wiring inductance can generate voltage transients which can cause problems. For minimal inductance and ground loops, the wires indicated by heavy lines (in Figure 22 and Figure 23) should be wide printed circuit traces and should be kept as short as possible. For best results, external components should be located as close to the switcher IC as possible using ground plane construction or single point grounding.

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If **open core inductors are used**, special care must be taken as to the location and positioning of this type of inductor. Allowing the inductor flux to intersect sensitive feedback, IC ground path, and C_{OUT} wiring can cause problems.

When using the adjustable version, special care must be taken as to the location of the feedback resistors and the associated wiring. Physically locate both resistors near the IC, and route the wiring away from the inductor, especially an open core type of inductor.

WSON PACKAGE DEVICES

The LM2672 is offered in the 16 lead WSON surface mount package to allow for increased power dissipation compared to the SOIC-8 and PDIP.

The Die Attach Pad (DAP) can and should be connected to PCB Ground plane/island. For CAD and assembly guidelines refer to Application Note AN-1187 at http://www.ti.com/lsds/ti/analog/powermanagement/power_portal.page.

SNVS136K - SEPTEMBER 1998-REVISED APRIL 2013



REVISION HISTORY

Ch	nanges from Revision J (April 2013) to Revision K	Pa	ge
•	Changed layout of National Data Sheet to TI format		23





11-Dec-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM2672LD-ADJ/NOPB	ACTIVE	WSON	NHN	16	1000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 125	S0004B	Samples
LM2672M-12	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	-40 to 125	2672 M-12	
LM2672M-12/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	2672 M-12	Sample
LM2672M-3.3	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	-40 to 125	2672 M3.3	
LM2672M-3.3/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	2672 M3.3	Sample
LM2672M-5.0	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	-40 to 125	2672 M5.0	
LM2672M-5.0/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	2672 M5.0	Sample
LM2672M-ADJ	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	-40 to 125	2672 MADJ	
LM2672M-ADJ/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	2672 MADJ	Sample
LM2672MX-12/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	2672 M-12	Sample
LM2672MX-3.3/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	2672 M3.3	Sample
LM2672MX-5.0	NRND	SOIC	D	8	2500	TBD	Call TI	Call TI	-40 to 125	2672 M5.0	
LM2672MX-5.0/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	2672 M5.0	Sample
LM2672MX-ADJ	NRND	SOIC	D	8	2500	TBD	Call TI	Call TI	-40 to 125	2672 MADJ	
LM2672MX-ADJ/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	2672 MADJ	Sample
LM2672N-12/NOPB	ACTIVE	PDIP	Р	8	40	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	-40 to 125	LM2672 N-12	Sample
LM2672N-3.3/NOPB	ACTIVE	PDIP	Р	8	40	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	-40 to 125	LM2672 N-3.3	Sample



PACKAGE OPTION ADDENDUM

11-Dec-2014

Orderable Device	Status	Package Type	_	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM2672N-5.0/NOPB	ACTIVE	PDIP	Р	8	40	Green (RoHS	CU SN	Level-1-NA-UNLIM	-40 to 125	LM2672	Samples
						& no Sb/Br)				N-5.0	bumpies
LM2672N-ADJ	LIFEBUY	PDIP	Р	8	40	TBD	Call TI	Call TI	-40 to 125	LM2672	
										N-ADJ	
LM2672N-ADJ/NOPB	ACTIVE	PDIP	Р	8	40	Green (RoHS	CU SN	Level-1-NA-UNLIM	-40 to 125	LM2672	Samples
						& no Sb/Br)				N-ADJ	Dantiple

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component has a RohS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

11-Dec-2014

In no event shall TI's liabilit	y arising out of such information	exceed the total purchase	price of the TI part(s) a	at issue in this document sold by	TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2672LD-ADJ/NOPB	WSON	NHN	16	1000	178.0	12.4	5.3	5.3	1.3	8.0	12.0	Q1
LM2672MX-12/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM2672MX-3.3/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM2672MX-5.0	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM2672MX-5.0/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM2672MX-ADJ	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM2672MX-ADJ/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2672LD-ADJ/NOPB	WSON	NHN	16	1000	213.0	191.0	55.0
LM2672MX-12/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM2672MX-3.3/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM2672MX-5.0	SOIC	D	8	2500	367.0	367.0	35.0
LM2672MX-5.0/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM2672MX-ADJ	SOIC	D	8	2500	367.0	367.0	35.0
LM2672MX-ADJ/NOPB	SOIC	D	8	2500	367.0	367.0	35.0

P (R-PDIP-T8)

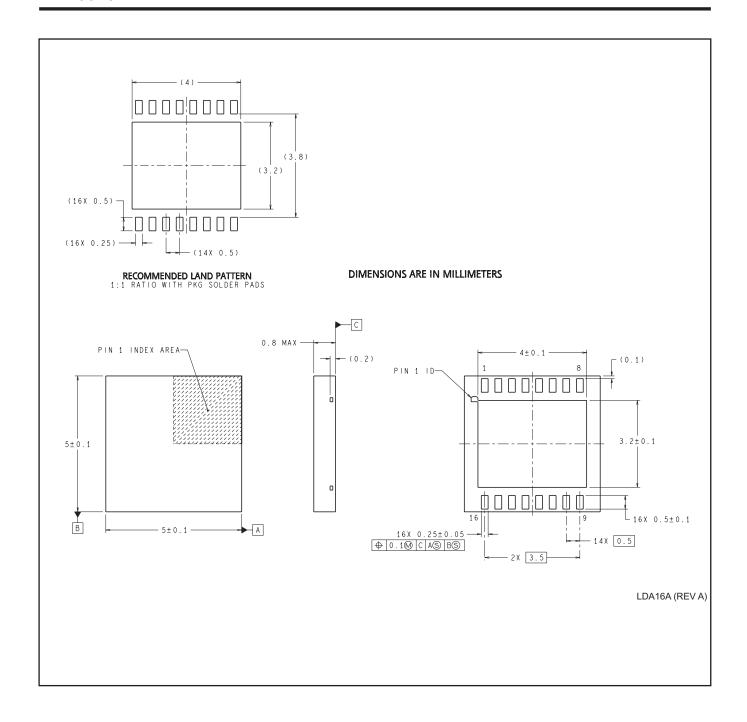
PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.





D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



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